



ヒートシンク一覧

maxiFLOW™



L: 15-45 mm
W: 15-45 mm
H: 7.5-19.5 mm

maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective air cooling.

Straight Fin



L: 15-45 mm
W: 15-45 mm
H: 7.5-24.5 mm

High aspect ratio straight fin extrusions with the best thermal performance in its class.

maxiFLOW™ Brick



L: 23-117 mm
W: 23-118 mm
H: 6-23 mm

maxiFLOW™ heat sinks, specially designed to cool 1/8, 1/4, 1/2 and full brick DC-DC power converters.

ASIC Cooling



Designed specifically for ASIC packages and their unique cooling requirements.

STAR LED



L: 18-85 mm
Dia: 45-100 mm

High-performance cooling solutions designed for high heat flux LEDs.

High Performance Extrusions



L: 10-60 mm
W: 10-60 mm
H: 2-25 mm

Over 1300 high performance specialty extrusions offered in 3 fin type configurations: straight fin, slant fin, and cross-cut.

maxiFLOW™ maxiGRIP™



L: 17-45 mm
W: 17-45 mm
H: 7.5-19.5 mm

maxiGRIP™ is a secure heat sink attachment that does not require holes in the PCB. For STD and low profile component heights 1.5-4.5 mm

Straight Fin maxiGRIP™



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fanSINK™



L: 27-45 mm
W: 27-45 mm
H: 9.5-24.5 mm
*fan not included

Cross-Cut heat sink with maxiGRIP™ attachment allows for the direct attachment of the fanSINK™ to the component.

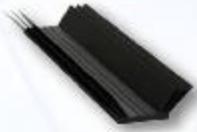
Flip-Chip Cooling



L: 21-62 mm
W: 32-52 mm
H: 9-16 mm

maxiFLOW™ custom designs for flip-chip components such as Freescale MPCs.

Linear LED



L: 305-330 mm
W: 45 mm
H: 26 mm

maxiFLOW™ design for cooling linear LED lighting products. Reduces temperatures by 50%

Stamped



Diverse range of board level applications. Over 74 different designs for varied applications.

maxiFLOW™ superGRIP™



L: 15-45 mm
W: 15-45 mm
H: 7.5-19.5 mm

superGRIP™ strong, uniform attachment force helps achieve maximum performance. Requires minimal space around components perimeter making it ideal for densely populated PCBs.

Straight Fin superGRIP™



L: 15-45 mm
W: 15-45 mm
H: 7.5-19.5 mm

superGRIP™ strong, uniform attachment force helps achieve maximum performance. Requires minimal space around components perimeter making it ideal for densely populated PCBs.

Push Pin



L: 40-41 mm
W: 38-45 mm
H: 10-25 mm

maxiFLOW™ push pin heat sinks based on industry standard hole patterns for a variety of device cooling applications.

LGA Cooling



High performance cooling solutions for high power LGA components.

Extrusions



L: 140-1524 mm
W: 41-483 mm
H: 10-73 mm

High performance aluminum extrusions provide cost-effective price points in over 120 profiles.

Cross-Cut



L: 15-45 mm
W: 15-45 mm
H: 7.5-24.5 mm

High aspect ratio cross-cut extrusions with the best thermal performance in its class.

Custom Designed Air and Liquid Cooling Solutions



ATS is world renowned for its custom designed solutions of over 5000 high- and ultra-performance heat sinks. From concept to production, ATS is positioned to meet all of your application-specific cooling and packaging requirements.

